NOTES:

1. FOR PCB LAYOUT SEE VICOR APPLICATION DRAWING 40438.
2. ROHS COMPLIANT PER CST.0001 LATEST REVISION.
3. THE SOLDERING METHOD USED FOR CHIPS (AND OPTIONAL HEATSINK GROUNDING) IS IMPORTANT WHEN SELECTING A THERMAL INTERFACE MATERIAL (TIM). THE PHASE-CHANGE TIM SHOWN IN THESE ILLUSTRATIONS MAY BE DAMAGED BY TEMPERATURES OVER 125°C. SO TWO ASSEMBLY PROCEDURES ARE DESCRIBED BELOW:
   [A] FOR HAND-SOLDERING ONLY
   [B] FOR WAVE-SOLDERING AND/OR HAND-SOLDERING.

[A] PLACE BOTTOM-SIDE HEATSINK (WITH PRE-ATTACHED PHASE-CHANGE TIM) ON PCB. PLACE CHIP AND TOP-SIDE HEATSINK (WITH PRE-ATTACHED TIM AND GROUNDING TABS). WHILE SUPPORTING PCB, INSERT PLASTIC PUSH-PINS THROUGH BOTH HEATSINKS AND PCB. SELECT PROPER PUSH-PIN LENGTH FROM TABLE ON THIS DRAWING.

IMPORTANT: TO SET FINAL THICKNESS OF PHASE-CHANGE TIM ENSURE THAT THE ENTIRE ASSEMBLY IS RAISED ABOVE 65°C FOR SEVERAL MINUTES. HAND-SOLDER ALL CHIP AND GROUNDING PINS. ADDITIONAL SOLDERING IRON HEAT MAY BE REQUIRED TO COMPENSATE FOR LOSSES TO THE HEATSINKS.

[B] WAVE SOLDERING TEMPERATURES ARE UNDESIRABLE FOR PLASTIC PUSH-PINS AND PHASE-CHANGE TIM, SO VICOR TM 40325 (PARKER CHOMERICS GEL8010) IS RECOMMENDED. APPLY A UNIFORM .003" (.076MM) LAYER OF TIM 40325 TO THE TOP AND BOTTOM SURFACE OF THE CHIP. OR TO THE CORRESPONDING HEATSINK SURFACE. PLACE BOTTOM-SIDE HEATSINK, CHIP, AND TOP-SIDE HEATSINK ON PCB. WITH A CUSTOM FIXTURE APPLY APPROX. 10 LBS LOAD TO THE TOP-SIDE HEATSINK AND THEN WAVE-SOLDER ALL PINS. REMOVE FIXTURE AND INSERT PLASTIC PUSH-PINS THROUGH BOTH HEATSINKS AND PCB. SELECT PROPER PUSH-PIN LENGTH FROM TABLE ON THIS DRAWING.

CARE SHOULD BE TAKEN TO AVOID FULLY COMPRESSING THE PUSH-PIN SPRING DURING INSTALLATION AS THIS WOULD EXPOSE THE CHIP TO FORCES GREATER THAN THE RECOMMENDED LIMIT OF 3.1 LBF (13.8 N) PER PUSH-PIN.

PUSH-PIN SELECTION

HEATSINK OPTIONS

<table>
<thead>
<tr>
<th>COLOR</th>
<th>PCB THE NOMINAL RANGE</th>
<th>PCB THE MINIMUM</th>
<th>PCB THE MAXIMUM</th>
</tr>
</thead>
<tbody>
<tr>
<td>32436</td>
<td>1.143 MM TO 1.854 MM (045&quot;)</td>
<td>1.041 MM (04&quot;)</td>
<td>2.057 MM (081&quot;)</td>
</tr>
<tr>
<td>32437</td>
<td>1.800 MM TO 2.088 MM (071&quot;)</td>
<td>1.676 MM (066&quot;)</td>
<td>2.293 MM (096&quot;)</td>
</tr>
</tbody>
</table>

PUSH-PINS
SEE NOTE 3, 4 AND SELECTION TABLE

GROUNDING TABS
SEE NOTE 3

THermal INTERFACE
SEE NOTE 3(A) OR 3(B)

SCREW (40578) INSTALLED FROM BOTTOM SIDE OF PCB. TORQUE TO 6 IN-LBS.

TOP HEATSINK
APPLICATION
SEE NOTES 3

BOTTOM HEATSINK
APPLICATION
SEE NOTE 3

CHIPS SHOWN HERE

6123 DUAL 11MM 40520 40528 -
6123 DUAL 19MM 40408 -
6123 DUAL 11MM 40519 40527
6123 DUAL 19MM 40409 -
6123 CHIP SHOWN HERE

ASSEMBLED FRONT VIEW